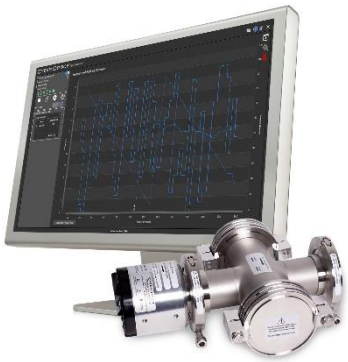
CyberOptics Demonstrates High-Precision Sensor Technology at Touch Taiwan

Minneapolis, Minnesota — April 7, 2021 — CyberOptics® Corporation (NASDAQ: CYBE), a leading global developer and manufacturer of high-precision 3D sensing technology solutions, will showcase the In-Line Particle Sensor™ (IPS), WaferSense® wireless measurement sensors and the NanoResolution Multi-Reflection Suppression™ (MRS™) sensor for inspection and metrology at the Touch Taiwan Exhibition on April 21-23rd at the Taipei Nangang Exhibition Center in Taiwan in booth M330.

Cyberoptics' In-Line Particle Sensor (IPS) with CyberSpectrum™ software detects particles in gas and vacuum lines 24/7 in semiconductor process equipment and other controlled environments. An extension of the industry-leading WaferSense® Airborne Particle Sensor (APS) technology that is documented by fabs as the Best-Known Method (BKM), the IPS quickly identifies, monitors and enables troubleshooting of particles down to 0.1µm. Process and equipment engineers can speed equipment qualification with 24/7 monitoring. They can compare past and present data, as well as one tool to another, and see the effects of cleaning, adjustments and repairs in real-time.



"The desire for a contamination-free process environment, coupled with stringent manufacturing requirements are driving the need for a best-in-class process to detect particles in gas and vacuum lines," said Dr. Subodh Kulkarni, President and CEO, CyberOptics, "The IPS can quickly identify when and where particles originate, as well as the source, saving significant time and expense while maximizing yields and tool uptimes."

The company will also display the NanoResolution MRS sensor that is integrated into CyberOptics' WX3000™ system for wafer-level and advanced packaging inspection and metrology. It provides sub-micrometer accuracy on features as small as 25µm. While retaining its ability to reject spurious multiple reflections, it adds the ability to capture and analyze specular reflections from shiny surfaces of solder balls, bumps and pillars, providing highly accurate inspection and metrology.

With data processing speeds in excess of 75 million 3D points per second, the WX3000 system delivers production-worthy throughput greater than 25 wafers (300mm) per hour. Complete 100% 3D/2D inspection can be accomplished two to three times faster than alternative technologies.

For more information, visit www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (www.cyberoptics.com) is a leading global developer and manufacturer of high-precision 3D sensing technology solutions. CyberOptics' sensors are used for inspection and metrology in the SMT and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the Company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of key vertical markets. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: a possible world-wide recession or depression resulting from the economic consequences of the COVID-19 pandemic; the negative effect on our revenue and operating results of the COVID-19 crisis on our customers and suppliers and the global supply chain; market conditions in the global SMT and semiconductor capital equipment industries; trade relations between the United States and China and other countries; the timing of orders and shipments of our products, particularly our 3D MRS SQ3000 Multi-Function systems and MX systems for memory module inspection; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics and semiconductor markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the market acceptance of our SQ3000 Multi-Function inspection and measurement systems and products for semiconductor advanced packaging inspection and metrology; costly and time consuming litigation with third parties related to intellectual property infringement; the negative impact on our customers and suppliers due to past and future terrorist threats and attacks and any acts of war; the impact of the MX3000 orders on our consolidated gross margin percentage in any future period; risks related to cancellation or renegotiation of orders we have received; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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For additional information, contact:

Carla Furanna
Vice President of Global Marketing, CyberOptics
952-820-5837, cfuranna@cyberoptics.com